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ERRATUM

Erratum to: Architectural Growth of Cu Nanoparticles Through Electrodeposition

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Unfortunately, the corresponding author name has been misspelled in the published version this paper.

Instead of Kaun-Jiuh Lin it should be Kuan-Jiuh Lin.

The online version of the original article can be found under doi:10.1007/s11671-009-9424-5.

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